

EOSL Exhibits

小晶片設計製造平台 Chiplet

1. 小晶片設計與系統解決方案
Chiplet Design and System Solutions
2. 低溫高密度細線寬線距混合鍵接合
Low Temperature Fine Pitch Hybrid Bonding
3. 內埋可程式晶片系統化 3D 整合技術
Embedded Programmable Chip 3D Integration Technology
4. ITRI 3D 可程式SiP - 膠囊內視鏡
ITRI 3D Programmable SiP - Capsule Endoscope
5. 千瓦級散熱方案
Thermal Solution for 1000W HPC Cooling
6. 高解析度環景影像校正晶片解決方案
High-resolution Panoramic Image Calibration Chip Solution
7. 全流程(IC-PKG-PCB)測試載板設計服務
Full Flow (IC-PKG-PCB) Test Loadboard Design Service
8. 扇外型晶圓級封裝共乘服務平台
FOWLP Shuttle Service Platform
9. 高精度電源量測單元
High Precision Source Measure Unit
10. AI 晶片系統軟體
AI Chip System Software
11. RISC-V 可延展運算架構技術
RISC-V Extensible Operation Architecture Technology
12. 人工智慧晶片設計實驗室
AI Chip Design Lab

車用電子 AE/EV

1. 智慧座艙之駕駛生理感知方向盤與適形化中控台
Bio-sensing Steering Wheel and Three-dimensional Conformal Console
2. 充電樁與車載充電器用碳化矽功率模組
SiC Power Module for EV Charging Solution
3. 30kW 全碳化矽直流快充功率單元 DC-DC 電路
30kW full Silicon Carbide (SiC) DC-DC Converter for Fast Charging Unit
4. 永續智慧能源系統
SENSE - Smart Energy for a Sustainable Ecosystem
5. 車用智慧視覺影像技術
AI Technology for Automotive Applications
6. 超高速動態視覺技術
Ultra-High-Speed Dynamic Vision Technology
7. 氮化鎵高功率與高頻技術
GaN on X-substrate Power and Rf HEMT
8. AiP 扇外型封裝模組
Fan-out Packaging Technology

面板級扇外型封裝 FOPLP

1. 面板級扇外型封裝整合技術
Fan-out Panel-Level Packaging Integration Technology
2. 通過G3.5試量產驗證之高均勻性電鍍銅製程解決方案
High-uniformity Electroplating Copper Process Solution Validated on G3.5 Panel Size Trial Production
3. 提升量產良率之適應形圖案化Chip First面板級扇外型封裝技術整合方案
Dynamic Die Shift Correction Technology for Enhancing Advanced IC Packaging Yield in Chip First FOPLP
4. 通過G3.5驗證之高解析低翹曲RDL First製程整合方案
High-Resolution RDL First Process Warpage Control Solution Verified on G3.5 Panel Size
5. 強化廠商專利群組之整合主被動元件面板級RDL技術
Technology of Thin Film Active and Passive Devices Integrated into RDL for Strengthening Panel Manufacturer's Patent Portfolio

其他技術 Other Technologies

1. 超高透明與超寬頻天線陣列技術
Ultra High Transparent Broadband Antenna Array Technology
2. 可水洗、高動態準確度之肌力感知智慧褲
Washable, High-dynamic-accuracy Contactless EMG Smart Pants
3. 氮化鎵射頻元件
GaN-based RF Devices
4. 應用於超導量子電腦之低溫控制電路
Cryo-CMOS Control/Readout Circuit for Superconducting Quantum Computer
5. 3.3kV高電壓碳化矽功率模組
3.3kV High SiC Power Module
6. 全碳化矽1.9kV/200kW高電壓功率單元
1.9kV/200kW High-Voltage Full Silicon Carbide (SiC) Power Unit
7. 面射型雷射
VCSEL



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